

### Features

- Green Device Available
- Super Low Gate Charge
- Excellent  $CdV/dt$  effect decline
- Advanced high cell density Trench technology

### Product Summary

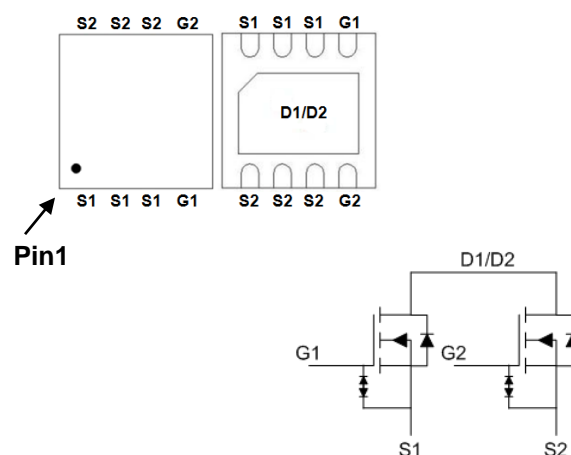
BVDSS	RDSON	ID
12V	4.3mΩ	56A

### General Description

The JHQ1030 is the low RDSON trenched N-CH MOSFETs with robust ESD protection. This product is suitable for Lithium-ion battery pack applications.

The JHQ1030 meet the RoHS and Green Product requirement with full function reliability approved.

### DFN3x3 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	12	V
$V_{GS}$	Gate-Source Voltage	$\pm 8$	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	56	A
$I_D @ T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	35.6	A
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	19	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	15	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	100	A
$P_D @ T_C=25^\circ C$	Total Power Dissipation <sup>1</sup>	31	W
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>1</sup>	3.6	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	35	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	4	$^\circ C/W$

**N-Channel Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=250\mu A$	12	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=4.5V$ , $I_D=3A$	2.3	3.3	4.3	$m\Omega$
		$V_{GS}=4.0V$ , $I_D=3A$	2.4	3.4	4.4	
		$V_{GS}=3.1V$ , $I_D=3A$	2.6	3.6	4.7	
		$V_{GS}=2.5V$ , $I_D=3A$	3	4	5.6	
		$V_{GS}=1.8V$ , $I_D=3A$	4	5.4	7.6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	0.4	0.6	1.0	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=12V$ , $V_{GS}=0V$ , $T_J=25^{\circ}\text{C}$	---	---	1	$\mu A$
		$V_{DS}=12V$ , $V_{GS}=0V$ , $T_J=55^{\circ}\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 8V$ , $V_{DS}=0V$	---	---	$\pm 10$	$\mu A$
$g_{fs}$	Forward Transconductance	$V_{DS}=5V$ , $I_D=3A$	---	42	---	S
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=10V$ , $I_D=3A$	---	38	---	$nC$
	Total Gate Charge (3.9V)		---	33	---	
$Q_{gs}$	Gate-Source Charge		---	4.5	---	
$Q_{gd}$	Gate-Drain Charge		---	12	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=10V$ , $V_{GS}=4.5V$ , $R_G=6\Omega$ $I_D=3A$	---	22	---	$ns$
$T_r$	Rise Time		---	41	---	
$T_{d(off)}$	Turn-Off Delay Time		---	77	---	
$T_f$	Fall Time		---	21	---	
$C_{iss}$	Input Capacitance	$V_{DS}=10V$ , $V_{GS}=0V$ , $f=1\text{MHz}$	---	3165	---	$pF$
$C_{oss}$	Output Capacitance		---	380	---	
$C_{rss}$	Reverse Transfer Capacitance		---	325	---	

**Diode Characteristics**

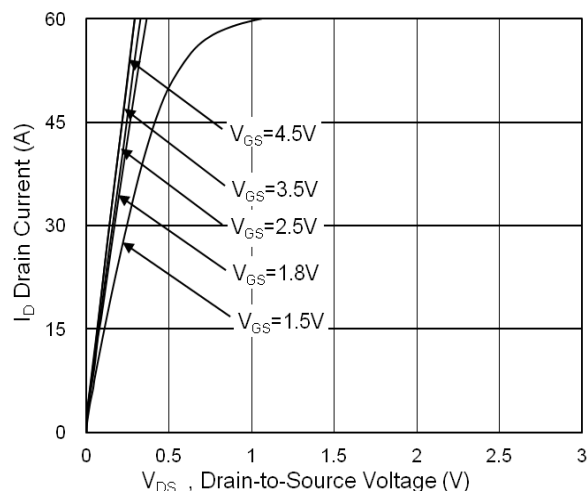
$I_S$	Continuous Source Current <sup>1</sup>	$V_G=V_D=0V$ , Force Current	---	---	30	A
$I_{SM}$	Pulsed Source Current <sup>2</sup>		---	---	100	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V$ , $I_S=3A$ , $T_J=25^{\circ}\text{C}$	---	---	1.2	V

Note :

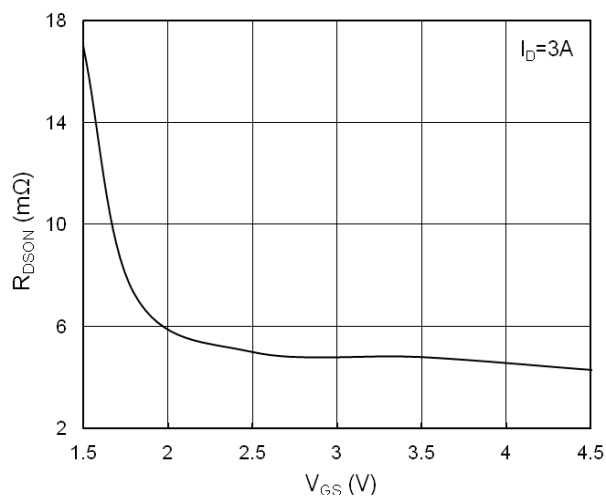
1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,  $t \leq 10s$ .

2.The data tested by pulsed , pulse width  $\leq 10\mu s$  , duty cycle  $\leq 1\%$

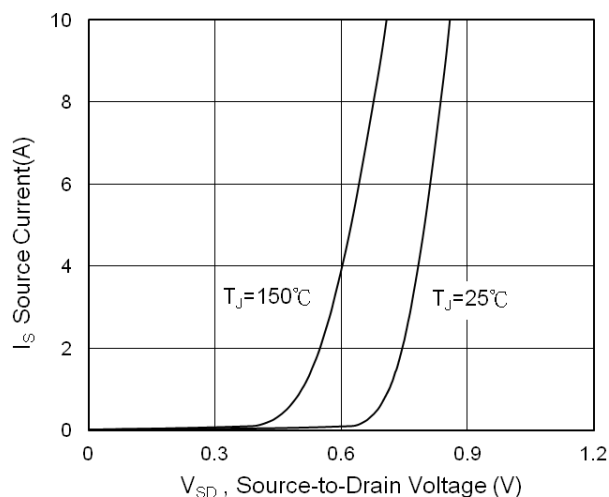
## Typical Characteristics



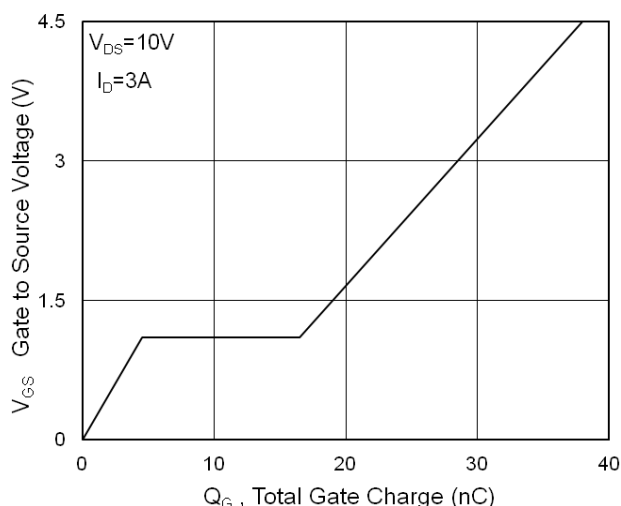
**Fig.1 Typical Output Characteristics**



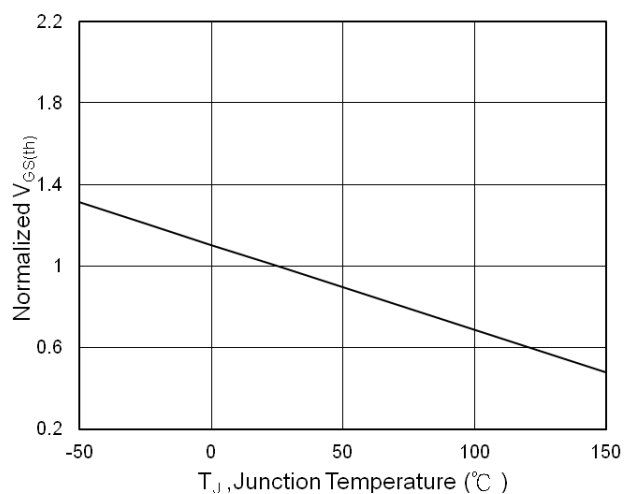
**Fig.2 On-Resistance vs. Gate-Source Voltage**



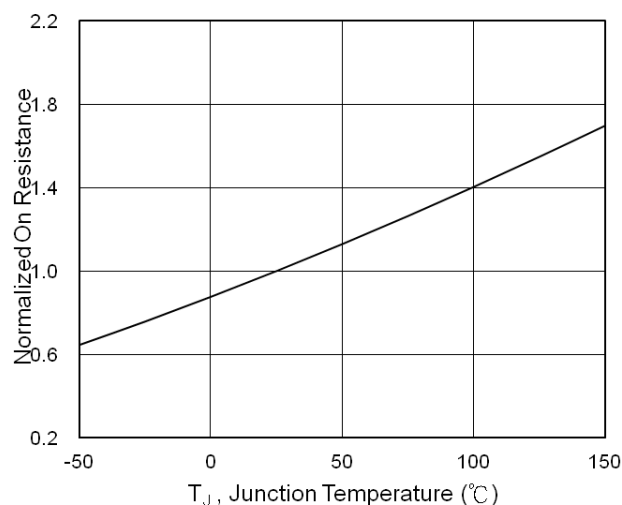
**Fig.3 Source Drain Forward Characteristics**



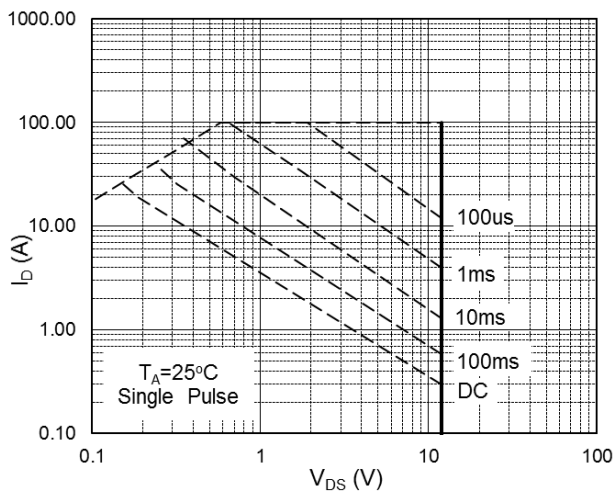
**Fig.4 Gate-Charge Characteristics**



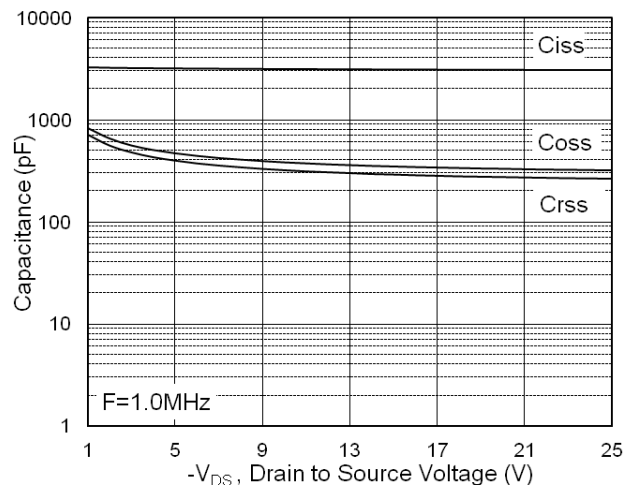
**Fig.5  $V_{GS(th)}$  vs.  $T_J$**



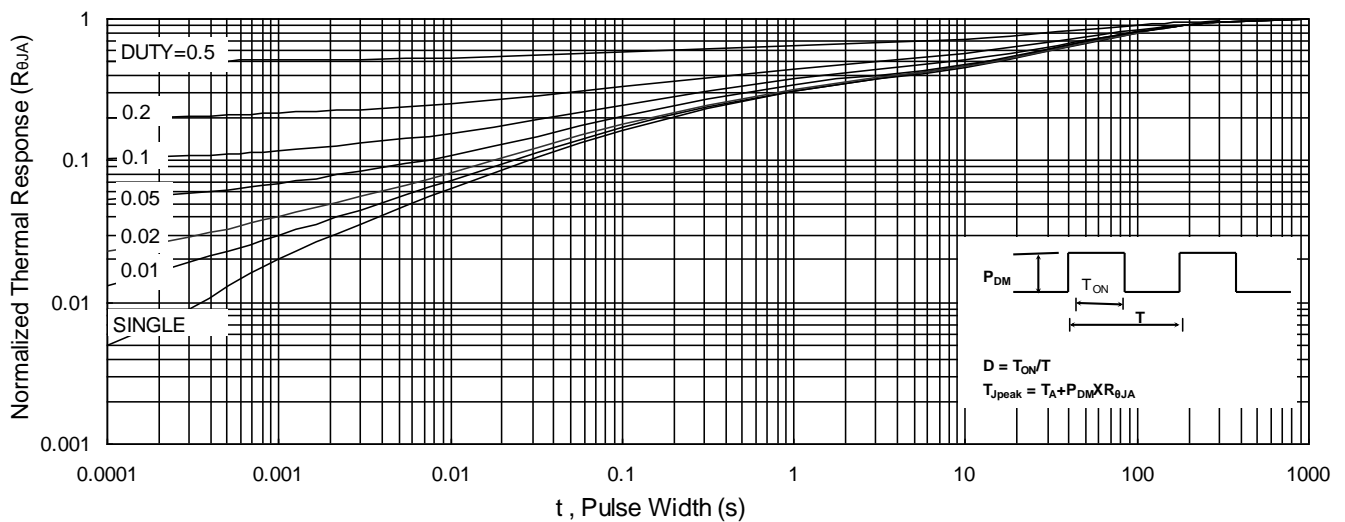
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



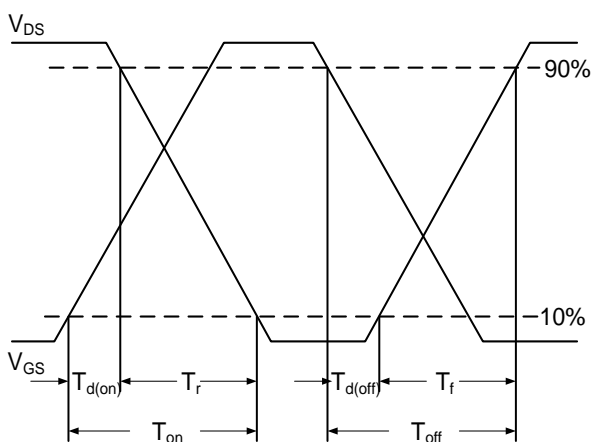
**Fig.7 Safe Operating Area**



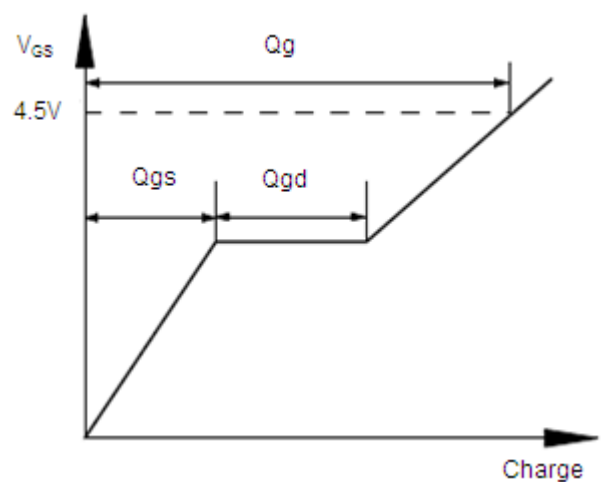
**Fig.8 Capacitance**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

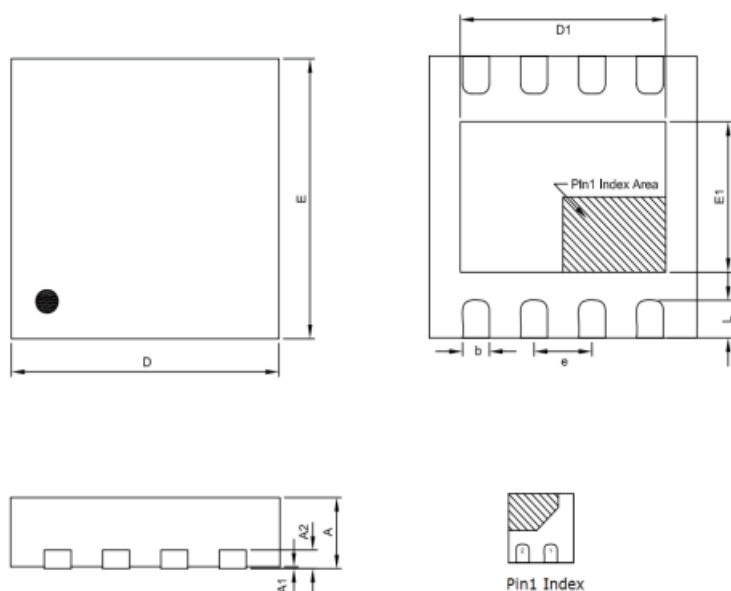


**Fig.10 Switching Time Waveform**



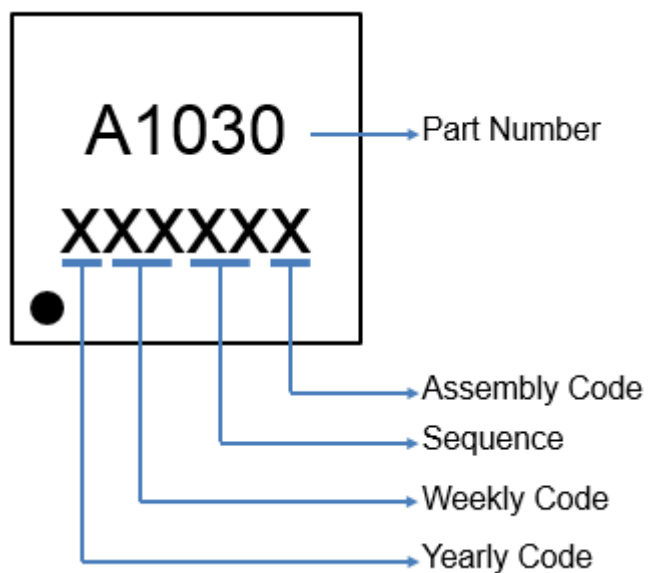
**Fig.11 Gate Charge Waveform**

## DFN3x3 Package Outline Dimensions

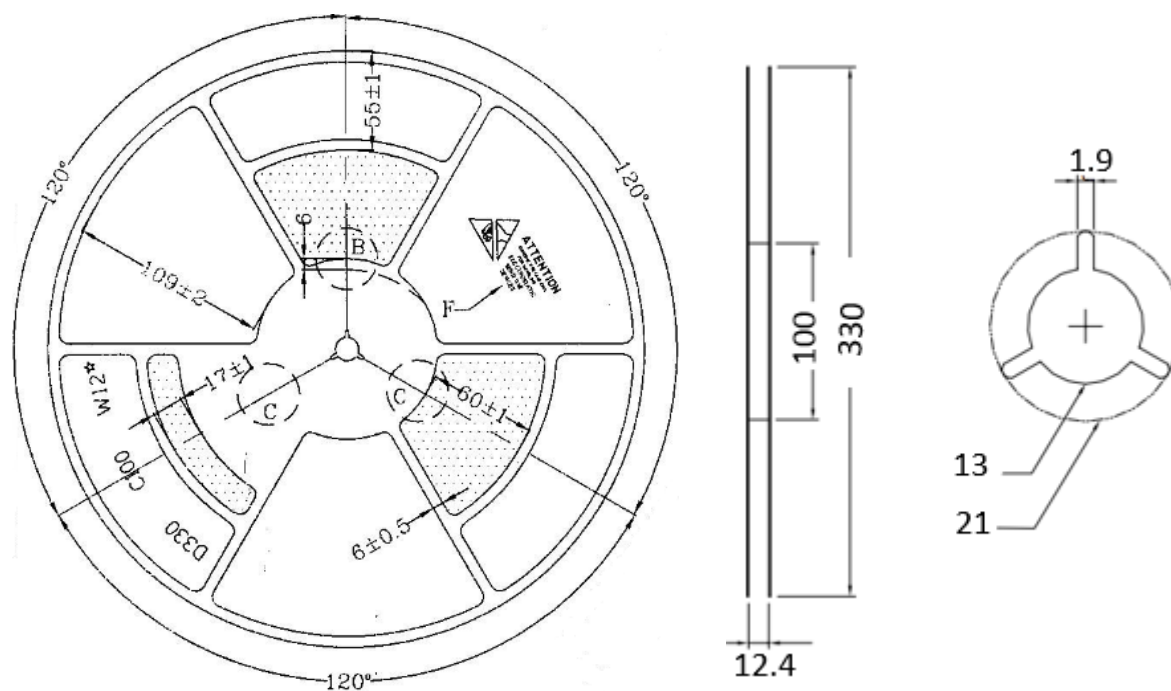
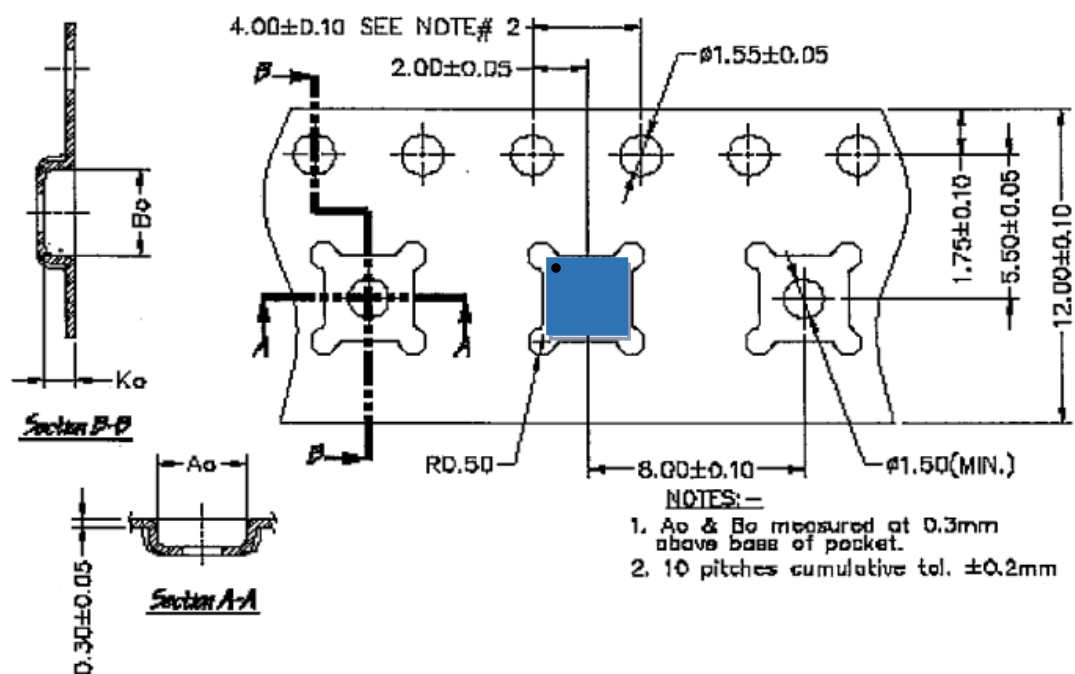


SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.0276	0.0295	0.0315
A1	0.00	--	0.05	0.000	--	0.002
A2	0.19	0.20	0.21	0.0075	0.0079	0.0083
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
D1	2.25	2.30	2.35	0.0886	0.0906	0.0925
E1	1.55	1.6	1.65	0.061	0.063	0.065
L	0.35	0.40	0.45	0.0138	0.0177	0.0207
b	0.25	0.30	0.35	0.0098	0.0118	0.0138
e	--	0.65	--	--	0.0256	--

## Marking Instruction



## DFN3x3 Tape and Reel Data



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